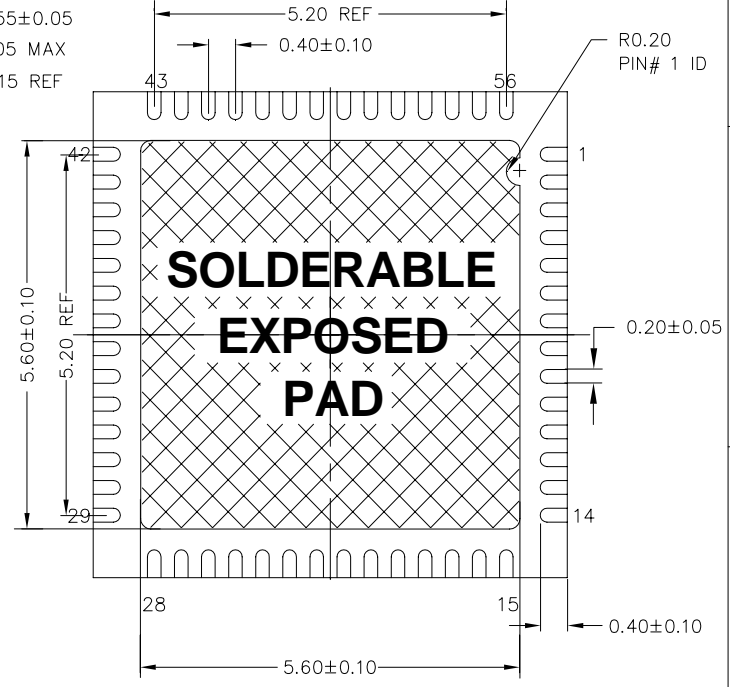
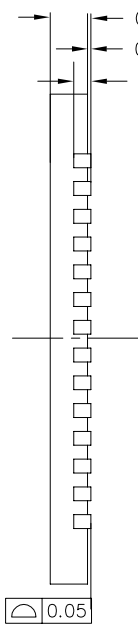
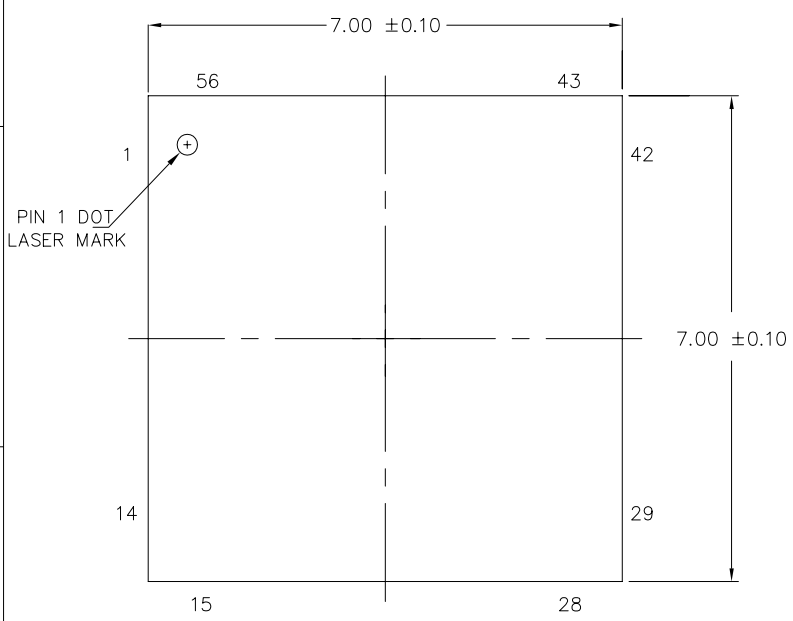


REVISIONS					
PAGE/ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
ALL	**	2840826	CREATED SPECS	1/7/10	BSC



**NOTES:**

1. HATCH AREA IS SOLDERABLE EXPOSED PAD
2. BASED ON REF JEDEC # MO-220
3. PACKAGE WEIGHT: 0.0928 grams
4. ALL DIMENSIONS ARE IN MILLIMETERS

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UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON: DECIMALS .XX ± 0.05 .XXX ± 0.025 .XXXX ± ANGLES ± 1°	DESIGNED BY	JSO	DATE	1/7/10		
	DRAWN BY	JSO	DATE	1/7/10		
	CHECKED BY	TSV	DATE	1/7/10		
	APPROVED BY	ECVI	DATE	1/7/10		
	MATERIAL	C7025, 0.15MM THICK	APPROVED BY	BSC	DATE	1/7/10

CYPRESS  
 Company Confidential  
 TITLE: PACKAGE OUTLINE DRAWING, 56LD QFN 7X7X0.6 MM LR56A/LQ56A 5.6X5.6 MM E-PAD (SAWN)  
 SIZE A PART # LR56A/LQ56A DWG NO 001-58740 REV \*\*  
 SCALED TO FIT ENG'G REV ENG 00 SHEET 1 OF 1